

# 60V N-Channel Enhancement Mode MOSFET

## **Description**

The SX12N06S uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## **General Features**

V<sub>DS</sub> = 60V I<sub>D</sub> =12A

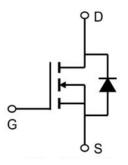
 $R_{DS(ON)} < 32m\Omega$  @  $V_{GS}=10V$ 

## **Application**

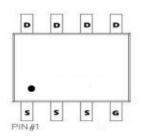
Battery protection

Load switch

Uninterruptible power supply







Absolute Maximum Ratings (Tc=25°Cunless otherwise noted

Symbol	Parameter	Rating	Units
Vos	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
lo@Tc=25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> 12		A
lo@Tc=100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	11	A
Ірм	Pulsed Drain Current <sup>2</sup>	36	A
EAS	Single Pulse Avalanche Energy³	25.5	mJ
P <b></b> □@Tc=25°C	Total Power Dissipation <sup>4</sup>	34.7	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
RөJA	Thermal Resistance Junction-Ambient <sup>1</sup>	85	°C/W
Rejc	Thermal Resistance Junction-Case <sup>1</sup>	28	°C/W

1



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# Electrical Characteristics (T\_J=25 $\,^{\circ}$ C, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
BVDSS	Drain-Source Breakdown Voltage	V <sub>G</sub> s=0V , I <sub>D</sub> =250uA	60	65		V	
△BVDSS/△TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃,Iɒ=1mA		0.063		V/°C	
(C) II	Static Drain-Source On-Resistance <sup>2</sup>	Vgs=10V , Ip=15A		24	32	mΩ	
RDS(ON)		Vgs=4.5V , ID=10A		33	42		
VGS(th)	Gate Threshold Voltage	V V 1 050 A	1.2	1.6	2.5	V	
riangleVGS(th)	V <sub>GS(th)</sub> Temperature Coefficient	Vgs=Vds , Id =250uA		-5.24		mV/℃	
IDOO	Drain-Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA	
IDSS		V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5		
IGSS	Gate-Source Leakage Current	Vgs=±20V , Vps=0V			±100	nA	
gfs	Forward Transconductance	VDS=5V , ID=15A		17		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		3.2		Ω	
Qg	Total Gate Charge (4.5V)			12.6			
Qgs	Gate-Source Charge	Vds=48V, Vgs=4.5V, Id=12A		3.2		nC	
$Q_{\mathrm{gd}}$	Gate-Drain Charge			6.3			
Td(on)	Turn-On Delay Time			8			
Tr	Rise Time	$V_{DD}$ =30 $V$ , $V_{GS}$ =10 $V$ , $R_{G}$ =3.3 $\Omega$ ,		14.2			
Td(off)	Turn-Off Delay Time	, RG-3.3Ω, ID=10A		24.4		ns	
Tf	Fall Time	.5 .07.		4.6			
Ciss	Input Capacitance			1378			
Coss	Output Capacitance	Vps=15V , Vgs=0V , f=1MHz		86		pF	
Crss	Reverse Transfer Capacitance			64			
ls	Continuous Source Current <sup>1,5</sup>	\/\/\/\			23	Α	
ISM	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			46	Α	
VSD	Diode Forward Voltage <sup>2</sup>	Vgs=0V , Is=1A , Tյ=25℃			1.2	V	

2  ${\tt www.sxsemi.com}$ 

Note:
1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

<sup>2 .</sup> The data tested by pulsed , pulse width  $\leq 300 us$  , duty cycle  $\leq 2\%$ 

<sup>3</sup> . The power dissipation is limited by  $150\,^{\circ}\!\mathrm{C}$  junction temperature

<sup>4</sup>  $\stackrel{\cdot}{\phantom{}_{\sim}}$  The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.





## **Typical Characteristics**

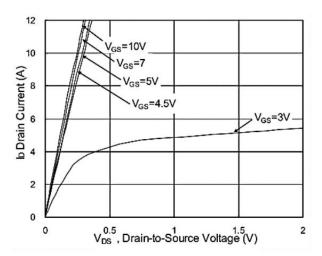


Fig.1 Typical Output Characteristics

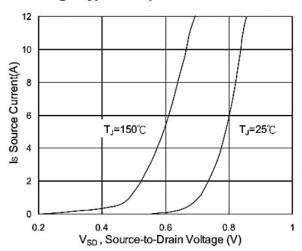


Fig.3 Forward Characteristics of Reverse

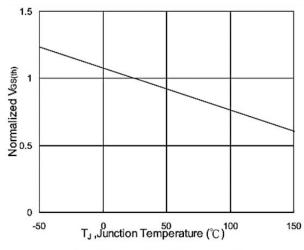


Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$ 

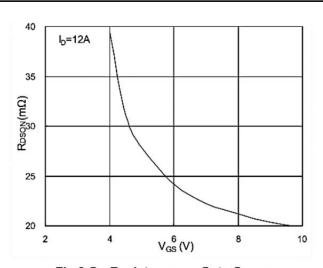


Fig.2 On-Resistance v.s Gate-Source

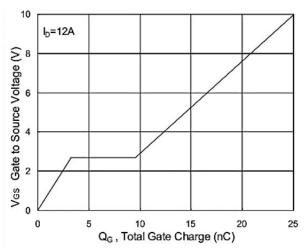


Fig.4 Gate-Charge Characteristics

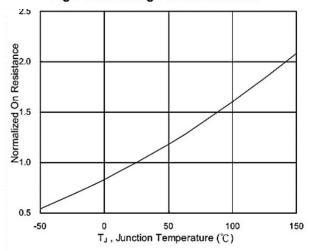
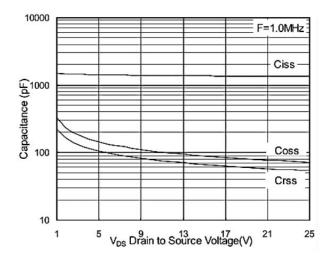


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>



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## **Typical Characteristics**



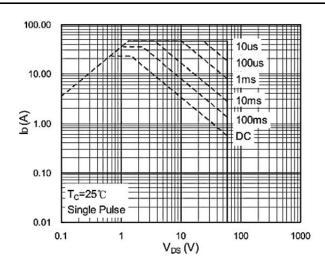


Fig.7 Capacitance

Fig.8 Safe Operating Area

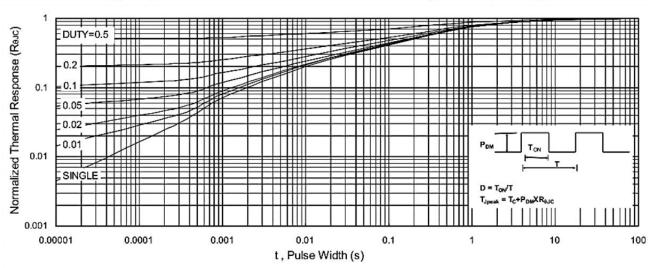


Fig.9 Normalized Maximum Transient Thermal Impedance

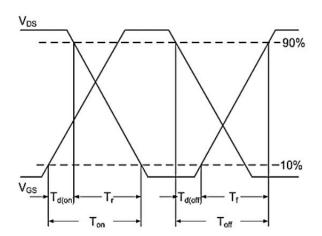


Fig.10 Switching Time Waveform

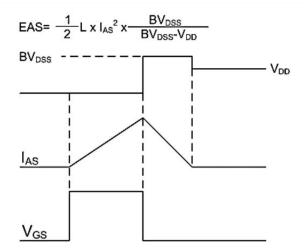
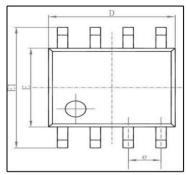
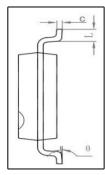


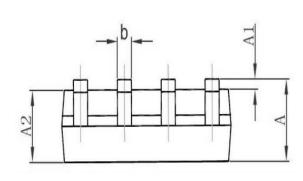
Fig.11 Unclamped Inductive Waveform



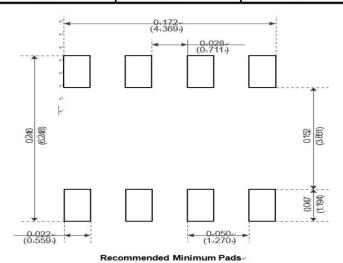
# Package Mechanical Data-SOP-8







Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
Α	1. 350	1. 750	0. 053	0.069
A1	0. 100	0. 250	0.004	0. 010
A2	1. 350	1. 550	0. 053	0.061
b	0. 330	0. 510	0. 013	0. 020
С	0. 170	0. 250	0.006	0. 010
D	4. 700	5. 100	0. 185	0. 200
E	3.800	4. 000	0. 150	0. 157
E1	5. 800	6. 200	0. 228	0. 244
е	1. 270 (BSC)		0. 050 (BSC)	
L	0. 400	1. 270	0. 016	0.050
θ	0°	8°	0°	8°



**Package Marking and Ordering Information** 

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Product ID	Pack	Marking	Qty(PCS)		
TAPING	SOP-8		3000		

5